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SKJERVEN  
MORRELL  
MACPHERSON LLP

Docket No.: AB-1134 US

April 26, 2001

Box Patent Application  
Commissioner For Patents  
Washington, D. C. 20231

Enclosed herewith for filing is a patent application, as follows:

Inventors: Byung Hoon Ahn, Jae Hun Ku, Young Suk Chung, Suk Gu Ko, Sung Sik Jang, Young Nam Choi, Won Chul Do

Title: Leadframe And Semiconductor Package Made Using The Leadframe

- X Return Receipt Postcard;  
X This Transmittal Letter (in duplicate);  
21 pages Specification (not including claims);  
4 pages Claims;  
1 page Abstract;  
7 Sheets of Drawings (Figs. 1a, 1b, 1c, 2a, 2b, 3a, 3b, 3c, 4a, 4b, 5a, 5b, 6a, 6b);  
3 pages Declaration For Patent Application and Power of Attorney (signed by Young Suk Chung, Suk Gu Ko, Sung Sik Jang, Young Nam Choi, Won Chul Do);  
1 page Recordation Form Cover Sheet (in duplicate); and  
3 ✓ pages Assignment (signed by Young Suk Chung, Suk Gu Ko, Sung Sik Jang, Young Nam Choi, Won Chul Do).

CLAIMS AS FILED

For	Number Filed		Number Extra		Rate		Basic Fee
Total Claims	20	-20	=	0	x	\$ 18.00	= \$ 0.00
Independent Claims	4	-3	=	1	x	\$80	= \$ 80.00
<input type="checkbox"/> Fee of _____ for the first filing of one or more multiple dependent claims per application							\$
<input type="checkbox"/> Fee for Request for Extension of Time							\$

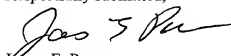
Please make the following charges to Deposit Account 19-2386:

- ☒ Total fee for filing the patent application in the amount of \$ 790.00  
☒ The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account 19-2386.

EXPRESS MAIL LABEL NO:

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Respectfully submitted,

  
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